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Dated: 8-9-2007 Signature:   
Nan Z. Carr

Docket No.: APPM/007385/PPC/ECP/CKIM  
1016.012390  
(PATENT)

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: §  
Deenesh Padhi, et al. §  
§ Group Art Unit: 1753  
Serial No.: 10/678,003 §  
§  
Confirmation No.: 9225 § Examiner: Edna Wong  
§  
Filed: October 2, 2003 §  
§  
For: HOMOGENEOUS §  
COPPER-PALLADIUM ALLOY §  
PLATING FOR ENHANCEMENT OF §  
ELECTRO-MIGRATION §  
RESISTANCE IN INTERCONNECTS §

### **AMENDMENT IN RESPONSE TO RESTRICTION REQUIREMENT**

MAIL STOP AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

### **INTRODUCTORY COMMENTS**

In response to the Restriction Requirement dated July 9, 2007, please amend the above-identified U.S. patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 5 of this paper.